

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
6 January 2005 (06.01.2005)

PCT

(10) International Publication Number
WO 2005/000527 A3

(51) International Patent Classification⁷: **B24D 3/32**,
B24B 37/04, B24D 13/14

(21) International Application Number:
PCT/US2004/017564

(22) International Filing Date: 3 June 2004 (03.06.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/463,680 17 June 2003 (17.06.2003) US

(71) Applicant: **CABOT MICROELECTRONICS CORPORATION** [US/US]; 870 North Commons Drive, Aurora, IL 60504 (US).

(72) Inventors: **PRASAD, Abaneshwar**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US). **SEVILLA, Roland, K.**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US). **LACY, Michael, S.**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US).

(74) Agents: **TURNER-BRIM, Phyllis, T.** et al.; Associate General Counsel, Intellectual Property, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US).

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM,

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for all designations*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

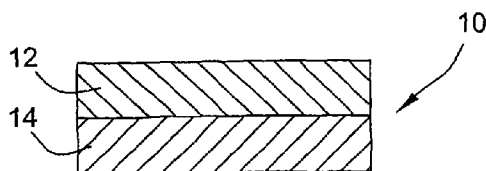
Published:

- *with international search report*
- *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
2 June 2005

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: MULTI-LAYER POLISHING PAD MATERIAL FOR CMP



(57) Abstract: The invention is directed to a multi-layer polishing pad (10) for chemical-mechanical polishing comprising a polishing layer (12) and a bottom layer (14), wherein the polishing layer and bottom layer are joined together without the use of an adhesive. The invention is also directed to a polishing pad comprising an optically transmissive multi-layer polishing pad material, wherein the layers of the polishing pad material are joined together without the use of an adhesive.

WO 2005/000527 A3